

Product Change Notice

Doc. No.: RF-008-0002 Revision: E

PCN-200917-02 C19_070_8 inch BSI products change from laser anneal process to High-K process _TSMC

Prepared By	Approval	
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Product Change Notice

PCN Number	200917-02	PCN Date	Nov-11, 2020	Effective Date	April-5, 2021
PCN Revision	0				
Title	TSMC 8 inch BSI products change from laser anneal process to High-K process				
Customer Contact	OV06946/OVM6946; OV06948/OVM6948; OV09728; OV05640 customers				
Proposed Ship Date		TBD		Sample Available date	End of Dec, 2020

PCN Details			
Description of Change			
 TSMC 8 inch BSI products to change from SiN Laser anneal process to High-K process. TSMC will phase out 8 inch laser anneal tool due to tool vendor end of service. There is no change to ordering part number. 			
Reason for Change			
Laser tool phase ou	it at TSMC		
Product Affected	OV06946-xxxx-xx; OVM6946-xxxx-xxxx; OV06948-xxxx-xx; OVM6948-xxxx-xxxx; OV09728-xxxx-xx; OV05640-xxxx-xx.		
Addition Information			
	rom Laser to High-K_ Summary (PCN_11112020)		

Notes: Customer should acknowledge receipt of PCN within 30 days. Lack of acknowledgement within 30 days constitutes change acceptance.



8 inch BSI products change from Laser process to High-K process _ Summary



Description:

- TSMC 8 inch BSI products change from SiN Laser anneal process to High-K process.
- TSMC will phase out 8 inch laser anneal tool due to vendor end of service.
- There is no change to ordering part number.

Qualify Plan and schedule:

- Reliability Qualification. (completed by Feb, 2021)
- Optical performance. (completed by Dec, 2020)

Product Affected:

- OV06946-xxxx-xx; OVM6946-xxxx-xxxx;
- OV06948-xxxx-xx; OVM6948-xxxx-xxxx;
- OV09728-xxxx-xx;
- OV05640-xxxx-xx.





SiN Laser anneal to High-K process change --- TSMC 8 inch BSI sensor

OVT

November 19, 2020

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What is changing?

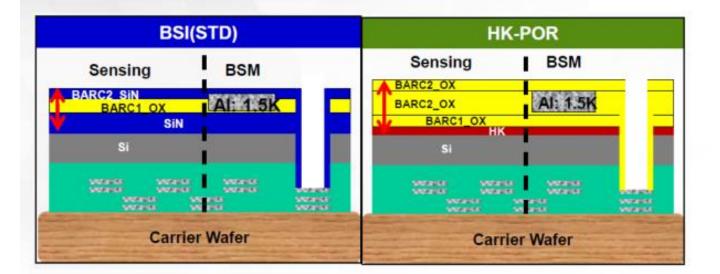
- > TSMC 8 inch BSI products to change from 'SiN Laser anneal' process to 'High-K' process.
- > TSMC will phase out 8" inch laser anneal tool due to tool vendor end of service.

Process change details

- The main purpose of Silicon Nitride (SiN) and High-K material is to act as Anti Reflecting Coating (ARC) and Si passivation layer.
- Both SiN stack and High-K stack (as shown by the red arrows in the picture) have similar n, and k values (n= Refractive Index, K= Dielectric constant) which ensures similar ARC properties. (see next page for cross section)



Process change details





Performance Summary

High-K over Laser anneal process

- Better Dark Current ,White Pixel, Noise, Large Photo Diode DINU, image mean, sensitivity, Full-Well Capacity and Quantum Efficiency performance
- All other parameters such as Color Ratio, Color Uniformity etc.. are comparable to that of laser anneal process

*** OV9728 production data is being collected and will be used to represent all products – Target will be completed by Mid-Dec

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Qualification plan

- High-K process is also qualified for all other key products including high volume MP products such as OV10642 / OX03A10 etc.
- OVT will follow standard qualification procedure and perform qualification, estimate completed by Feb 2021 or sooner.



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